

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:
an antenna;
an integrated circuit comprising a thin film transistor;
a light-receiving element; and
a light-emitting element,

wherein the light-emitting element and the light-receiving element each have a layer for conducting photoelectric conversion using a non-single crystal thin film, [[and]]
wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna, and

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit on the same substrate.

2. (Currently Amended) A semiconductor device comprising:
an antenna;
an integrated circuit comprising a thin film transistor;
a light-receiving element; and
a light-emitting element,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, [[and]]
wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the same substrate.

3. (Currently Amended) A semiconductor device comprising:

an antenna;

an integrated circuit comprising a thin film transistor;

a light-receiving element; and

a light-emitting element,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, [[and]]

wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna, and

wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed on the same substrate.

4. (Currently Amended) A semiconductor device comprising:

an integrated circuit;

a light-receiving element; and

a light-emitting element,

wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from configured to rectify an alternating current signal that is input to the connection terminal voltage generated by an antenna, a power supply circuit configured to generate a power supply voltage by using a voltage outputted from the rectification circuit, a demodulation circuit, and a logic circuit, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the same substrate.

5. (Currently Amended) A semiconductor device comprising:
- an antenna;
- an integrated circuit comprising a thin film transistor;
- a light-receiving element; and
- a light-emitting element,
- wherein the light-emitting element and the light-receiving element each have a layer for conducting photoelectric conversion using a non-single crystal thin film,
- wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit,
- wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate with an adhesive agent, and
- ~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.~~
- wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna.

6. (Currently Amended) A semiconductor device comprising:
- an antenna;
- an integrated circuit comprising a thin film transistor;
- a light-receiving element; and
- a light-emitting element,
- wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit,
- wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate with an adhesive agent, and

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.~~

wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna.

7. (Currently Amended) A semiconductor device comprising:

an antenna;

an integrated circuit comprising a thin film transistor;

a light-receiving element; and

a light-emitting element,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit,

wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate with an adhesive agent, and

~~wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the second substrate.~~

wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna.

8. (Currently Amended) A semiconductor device comprising:

an integrated circuit;

a light-receiving element; and

a light-emitting element,

wherein the integrated circuit comprises a connection terminal, a rectification circuit that generates power supply voltage from configured to rectify an alternating

~~current signal that is input to the connection terminal voltage generated by an antenna, a power supply circuit configured to generate a power supply voltage by using a voltage outputted from the rectification circuit, a demodulation circuit, and a logic circuit,~~

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed integrally, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are ~~formed over a first substrate and then separated therefrom, and attached to a second substrate with an adhesive agent, and~~

~~wherein the integrated circuit, the light-emitting element and the light receiving element are formed on the second substrate.~~

9. (Currently Amended) The semiconductor device according to any one of Claims 5 to 8, wherein the ~~first substrate is a glass substrate and the second substrate is a plastic substrate.~~

10. (Currently Amended) An IC card comprising:

an antenna;

an integrated circuit comprising a thin film transistor;

a light-receiving element; and

a light-emitting element,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit, [[and]]

wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the same substrate.

11. (Previously Presented) The IC card according to claim 10, wherein the antenna, the integrated circuit, the light-emitting element and the light-receiving element are formed on the same substrate.

12. (Currently Amended) An IC card comprising:

an integrated circuit;
a light-receiving element; and
a light-emitting element,

wherein the integrated circuit comprises a connection terminal, a rectification circuit ~~that generates power supply voltage from~~ configured to rectify an alternating current signal ~~that is input to the connection terminal~~ voltage generated by an antenna, a power supply circuit configured to generate a power supply voltage by using a voltage outputted from the rectification circuit, a demodulation circuit, and a logic circuit, and

wherein the integrated circuit, the light-emitting element and the light-receiving element are formed on the same substrate.

13. (Currently Amended) An IC card comprising:

an antenna;
an integrated circuit comprising a thin film transistor;
a light-receiving element; and
a light-emitting element,

wherein the antenna, the light-emitting element and the light-receiving element are electrically connected to the integrated circuit,

wherein the integrated circuit, the light-emitting element and the light-receiving element are ~~formed over a first substrate and then separated therefrom, and attached to a second substrate with an adhesive agent, [[and]]~~

~~wherein the integrated circuit, the light-emitting element and the light receiving element are formed on the second substrate.~~

wherein the integrated circuit includes a power supply circuit configured to generate a power supply voltage by using an alternating voltage generated by the antenna.

14. (Currently Amended) The IC card according to claim 13, wherein the antenna and the integrated circuit in addition to the light-emitting element and the light-receiving element are formed over the first substrate and then separated therefrom, and attached to the second substrate with an adhesive agent.

15. (Currently Amended) The IC card according to claim 12, wherein the integrated circuit, the light-emitting element and the light-receiving element are formed over a first substrate and then separated therefrom, and attached to a second substrate with an adhesive agent.

16. (Currently Amended) The IC card according to any one of Claims 13 to 15, wherein the first substrate is a glass substrate and the second substrate is a plastic substrate.